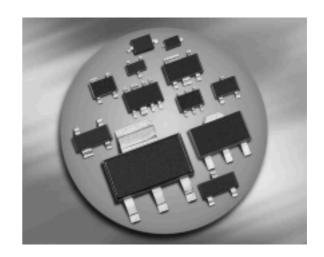


### **Medium Power AF Schottky Diode**

Forward current: 750 mA
Reverse voltage: 40 V

• For low-loss, fast-recovery, meter protection, bias isolation and clamping applications



#### **BAT165**



### ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Package	Configuration	Marking
BAT165	SOD323	single	C/White

### **Maximum Ratings** at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage <sup>1)</sup>	$V_{R}$	40	V
Forward current <sup>1)</sup>	I <sub>F</sub>	750	mA
Average rectified forward current (50/60Hz, sinus)	I <sub>FAV</sub>	500	mA
Non-repetitive peak surge forward current	I <sub>FSM</sub>	2.5	Α
( <i>t</i> ≤ 10ms)			
Total power dissipation	P <sub>tot</sub>	600	mW
<i>T</i> <sub>S</sub> ≤ 93°C			
Junction temperature	$ T_{i} $	150	°C
Storage temperature	$T_{\rm stg}$	-65 150	

#### **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	R <sub>thJS</sub>	≤ 95	K/W

1

<sup>&</sup>lt;sup>1</sup>For  $T_A$  > 25°C the derating of  $V_R$  and  $I_F$  has to be considered. Please refer to the atteched curves.

 $<sup>^{2}</sup>$ For calculation of  $R_{\mathrm{thJA}}$  please refer to Application Note Thermal Resistance



**Electrical Characteristics** at  $T_A$  = 25°C, unless otherwise specified

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
DC Characteristics	·				
Reverse current <sup>1)</sup>	I <sub>R</sub>				μA
$V_{R} = 30 \text{ V}$		-	-	12	
V <sub>R</sub> = 40 V		-	-	50	
$V_{R}$ = 40 V, $T_{A}$ = 65 °C		-	-	900	
Forward voltage	V <sub>F</sub>				V
$I_{\rm F}$ = 10 mA		0.23	0.315	0.4	
$I_{\rm F}$ = 100 mA		0.32	0.39	0.47	
$I_{\rm F}$ = 250 mA		0.35	0.44	0.54	
$I_{\rm F} = 750  \text{mA}$		0.44	0.58	0.74	
AC Characteristics					
Diode capacitance	C <sub>T</sub>	_	8.4	12	pF
$V_{R} = 10 \text{ V}, f = 1 \text{ MHz}$					

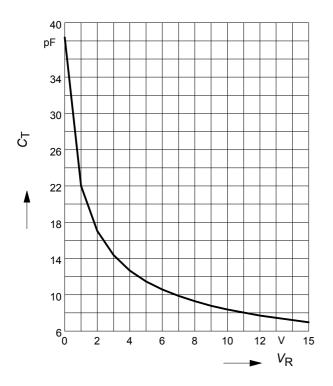
2

<sup>&</sup>lt;sup>1</sup>Pulsed test:  $t_p$  = 300 µs; D = 0.01



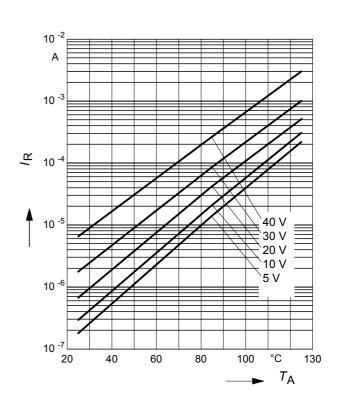
## **Diode capacitance** $C_T = f(V_R)$

f = 1MHz



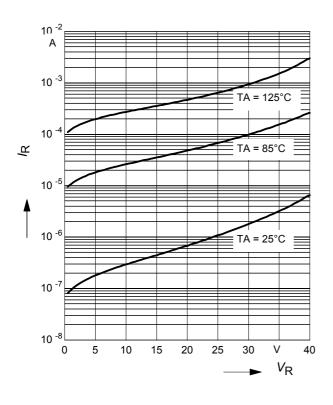
## Reverse current $I_R = f(T_A)$

 $V_{\mathsf{R}}$  = Parameter



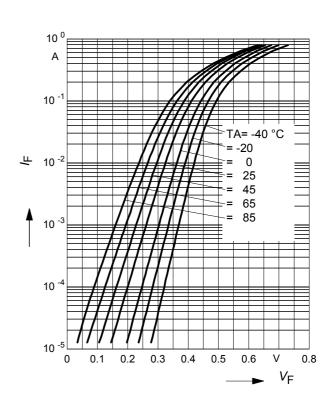
# Reverse current $I_R = f(V_R)$

 $T_A$  = Parameter



# Forward current $I_F = f(V_F)$

 $T_A$  = Parameter

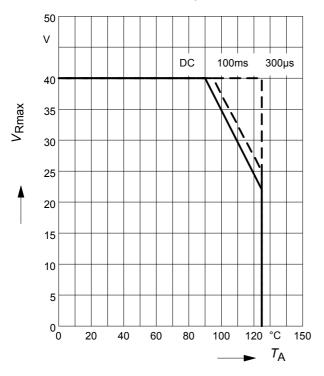




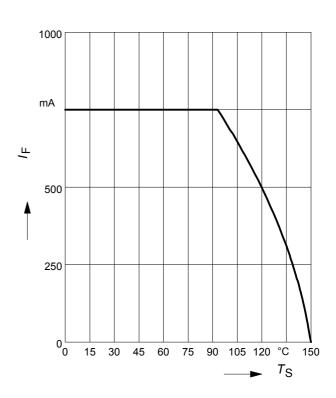
## Permissible Reverse voltage $V_R = f(T_A)$

 $t_p$  = Parameter, Duty cycle < 0.01

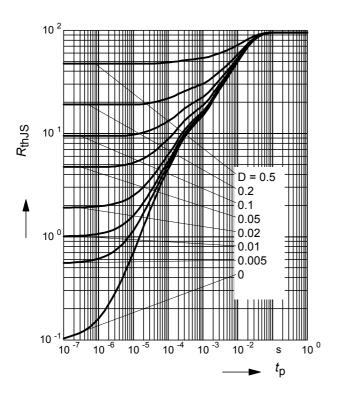
Device mounted on PCB with  $R_{th}$  = 160 k/W



## Forward current $I_F = f(T_S)$

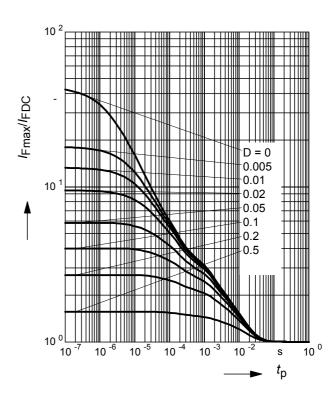


# Permissible Puls Load $R_{thJS} = f(t_p)$



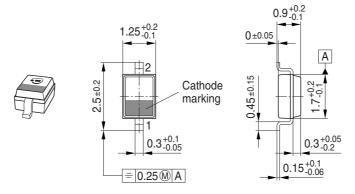
#### **Permissible Pulse Load**

$$I_{\text{Fmax}}/I_{\text{FDC}} = f(t_{\text{p}})$$

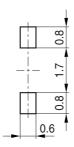




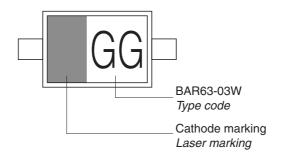
# Package Outline



### Foot Print

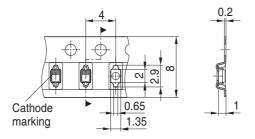


### Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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6 2006-05-12